



Attorney Docket SEL 173

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of)
Ohtani et al.)
Serial No.: 09/535,836)
Filed: March 28, 2000)
For: Semiconductor Device Having)
Multi-layer Wiring)
Art Unit: 2811)
Examiner: H. Vu)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:
the Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450 on

MAY 21, 2003

(Date of Deposit)

Shannon Wallace

Name of applicant, assignee, or Registered Rep.

Shannon Wallace 5/21/03

Signature

Date

TECHNOLOGY CENTER 2800
RECEIVED
MAY 30 2003

Sir:

In response to the Final Rejection dated January 22, 2003, a one month extension of time being separately submitted, please enter the following amendment in the above identified application:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Third Amendment) A semiconductor device comprising:
a first insulating film comprising an organic material formed over a conductive layer;
a first metallic layer formed on said first insulating film;
a second metallic layer formed on said first metallic layer;
a second insulating film formed on said second metallic layer; and